

L Number	Hits	Search Text	DB	Time stamp
1	1	"6131088"	JPO; DERWENT	2004/06/28 17:00
2	2	"61031088"	JPO; DERWENT	2004/06/28 17:00
3	1	"06131088"	JPO; DERWENT	2004/06/28 17:00
4	0	"406131088"	JPO; DERWENT	2004/06/28 17:00
-	210846	(chip or die or device or package) and (substrate or board or pcb or pwb) and (adhesive or bonding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 14:38
-	85527	((chip or die or device or package) and (substrate or board or pcb or pwb) and (adhesive or bonding) ) and (@ad<19960905)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 14:36
-	312	((chip or die or device or package) and (substrate or board or pcb or pwb) and (adhesive or bonding) ) and (@ad<19960905)) and (((adhesive or bonding) and (stress or deformation or cte)) with (change or shape))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 14:43
-	491	((chip or die or device or package) and (substrate or board or pcb or pwb) and (adhesive or bonding) ) and (@ad<19960905)) and (((adhesive or bonding) and (stress or deformation or cte or expansion or shrink or shrinkage)) with (change or shape))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 12:56
-	232	((chip or die or device or package) and (substrate or board or pcb or pwb) and (adhesive or bonding) ) and (@ad<19960905)) and (((adhesive or bonding) and (stress or deformation or cte or expansion or shrink or shrinkage)) with (change or shape)) ) and ((adhesive or bonding) same (gap or gaps or space or spaces or bubble or void or voids or vacuum))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 14:32
-	2978	((adhesive or bonding) and (deform or deformable or shange or shape)) with air	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 14:41
-	1496	((adhesive or bonding) and (deform or deformable or shange or shape)) with air ) and (@ad<19960905)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 14:43
-	200	((adhesive or bonding) and (deform or deformable or shange or shape)) with air ) and (@ad<19960905)) and (chip or die or device or package) and (substrate or board or pcb or pwb)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 14:37
-	194	((adhesive or bonding) and (deform or deformable or shange or shape)) with air ) and (@ad<19960905)) and (chip or die or device or package) and (substrate or board or pcb or pwb) ) not (((chip or die or device or package) and (substrate or board or pcb or pwb) and (adhesive or bonding) ) and (@ad<19960905)) and (((adhesive or bonding) and (stress or deformation or cte or expansion or shrink or shrinkage)) with (change or shape)) ) and ((adhesive or bonding) same (gap or gaps or space or spaces or bubble or void or voids or vacuum)) )	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 14:37

-	68	(((((adhesive or bonding) and (deform or deformable or shange or shape)) with air ) and (@ad<19960905)) and (chip or die or device or package) and (substrate or board or pcb or pwb) ) not (((chip or die or device or package) and (substrate or board or pcb or pwb) and (adhesive or bonding) ) and (@ad<19960905)) and (((adhesive or bonding) and (stress or deformation or cte or expansion or shrink or shrinkage)) with (change or shape)) ) and ((adhesive or bonding) same (gap or gaps or space or spaces or bubble or void or voids or vacuum)) )) and ((chip or die or device or package) with (adhesive or bonding))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 14:38
-	0	257/783.ccls and ((adhesive or bonding) and (deform or deformable or shange or shape)) with air	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 14:42
-	0	257/783.ccls. and ((adhesive or bonding) and (deform or deformable or shange or shape)) with air	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 14:42
-	18	257/783.ccls. and (((adhesive or bonding) and (stress or deformation or cte)) with (change or shape))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 14:45
-	2	(257/783.ccls. and (((adhesive or bonding) and (stress or deformation or cte)) with (change or shape)) ) and (@ad<19960905)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 14:43
-	5	257/795.ccls. and (((adhesive or bonding) and (stress or deformation or cte)) with (change or shape))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 16:59